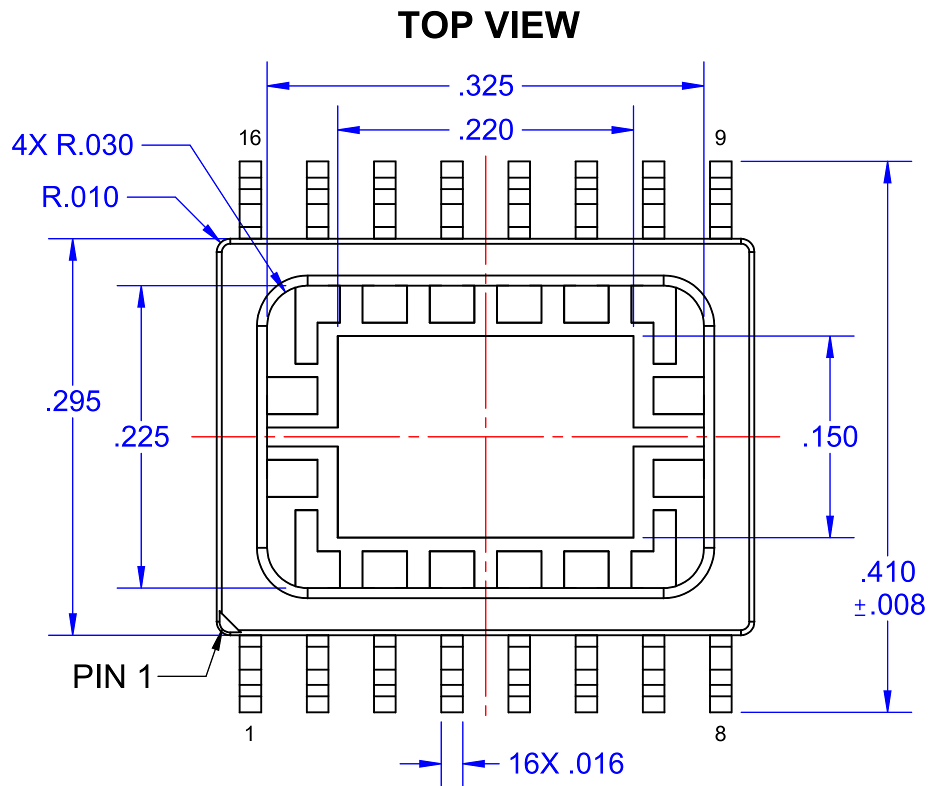
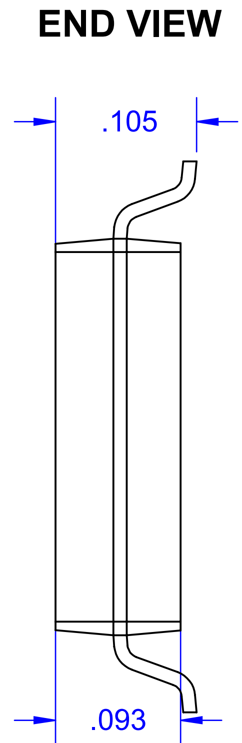
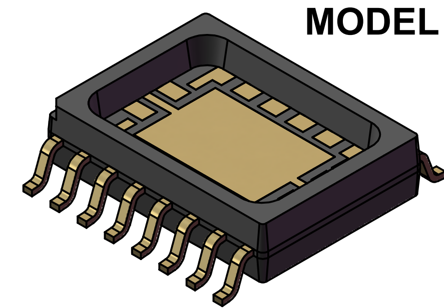
TOP VIEW

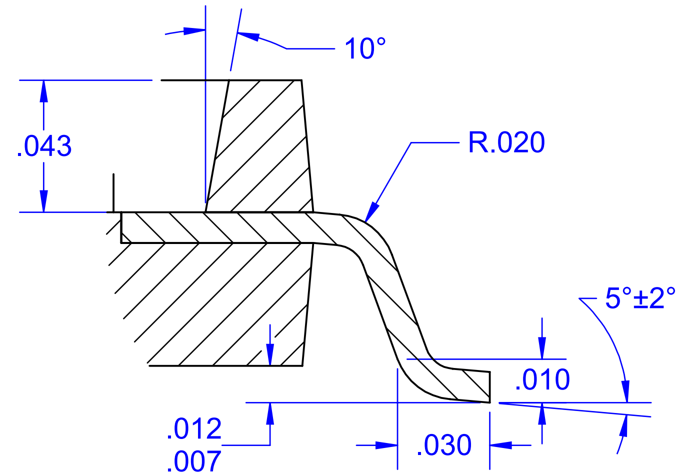


END VIEW



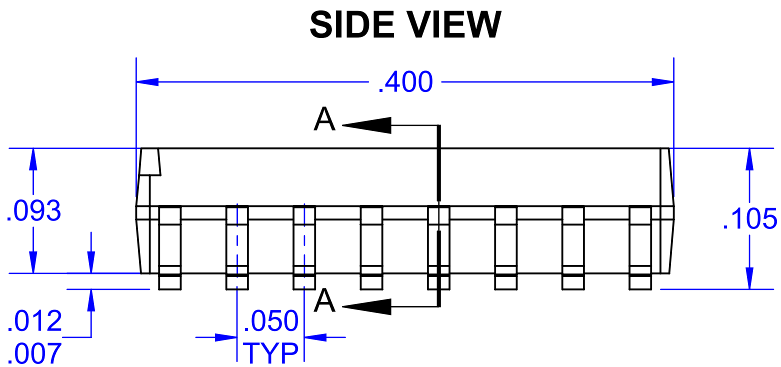
MODEL



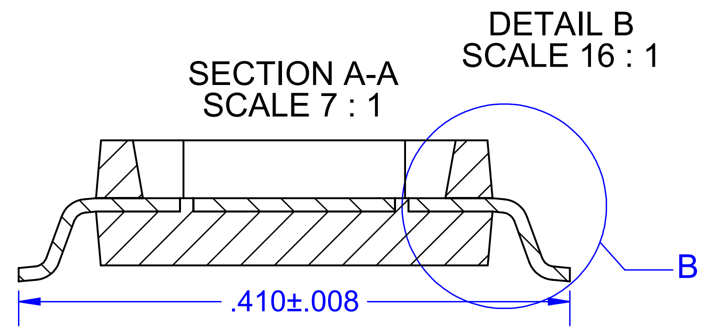


DETAIL B
SCALE 16 : 1

SIDE VIEW



SECTION A-A
SCALE 7 : 1

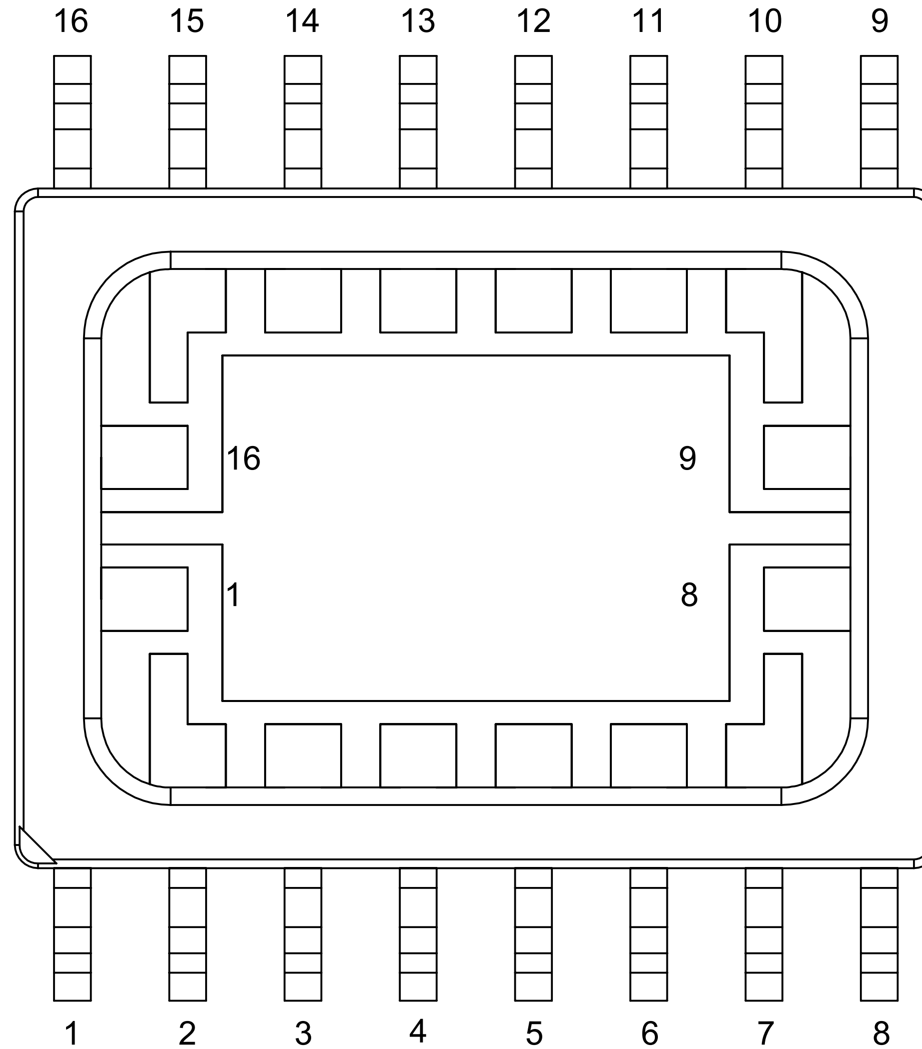


Notes: (Unless Otherwise Specified).

1) DIMENSIONS: INCHES [MM].
2) PACKAGE CONFORMS TO JEDEC MS-013.
3) BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.
4) LEAD FRAME: COPPER ALLOY A194 FULL HARD.
5) PLATING: NICKEL 100~300 MICROINCHES (2.5~7.6μm) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.

APPROVALS		DATE	Mirror Semiconductor™			
DRAWN	T.Au	2/11/2021				
ENG	M. Hart	2/11/2021	TITLE	SOL 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
MFG						
QA			SCALE 7:1	SIZE A	DRAWING NO. 120216	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 4	

BOND DIAGRAM



TITLE	SOL 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 10:1	SIZE A	DRAWING NO. 120216	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 4	

MODEL

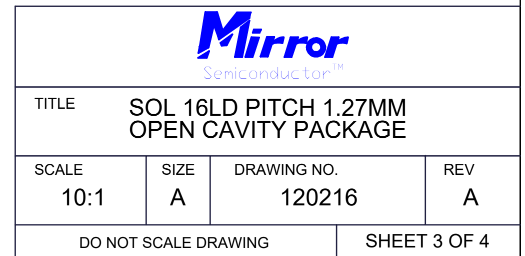
BOTTOM

9

1

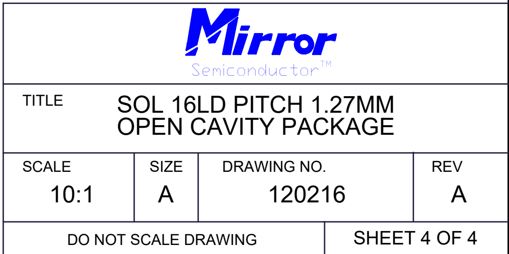
TOP

8



TITLE	SOL 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 10:1	SIZE A	DRAWING NO. 120216	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 4	

SUGGESTED PCB LAND PATTERN



TITLE	SOL 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 10:1	SIZE A	DRAWING NO. 120216	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 4	